

GP 2811

**CERTIFICATE OF MAILING BY FIRST CLASS MAIL (37 CFR 1.8)**

Applicant(s): Jack H. Linn, et al.

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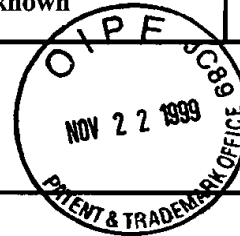
Examiner

Unknown

Group Art Unit

2811

Invention: **BONDED WAFER WITH METAL SILICIDATION**



I hereby certify that this **IDS w/Form PTO-1449 (5 pgs)**

*(Identify type of correspondence)*

is being deposited with the United States Postal Service as first class mail in an envelope addressed to: The

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**November 18, 1999**

*(Date)*

**Penny R. Turrell**

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